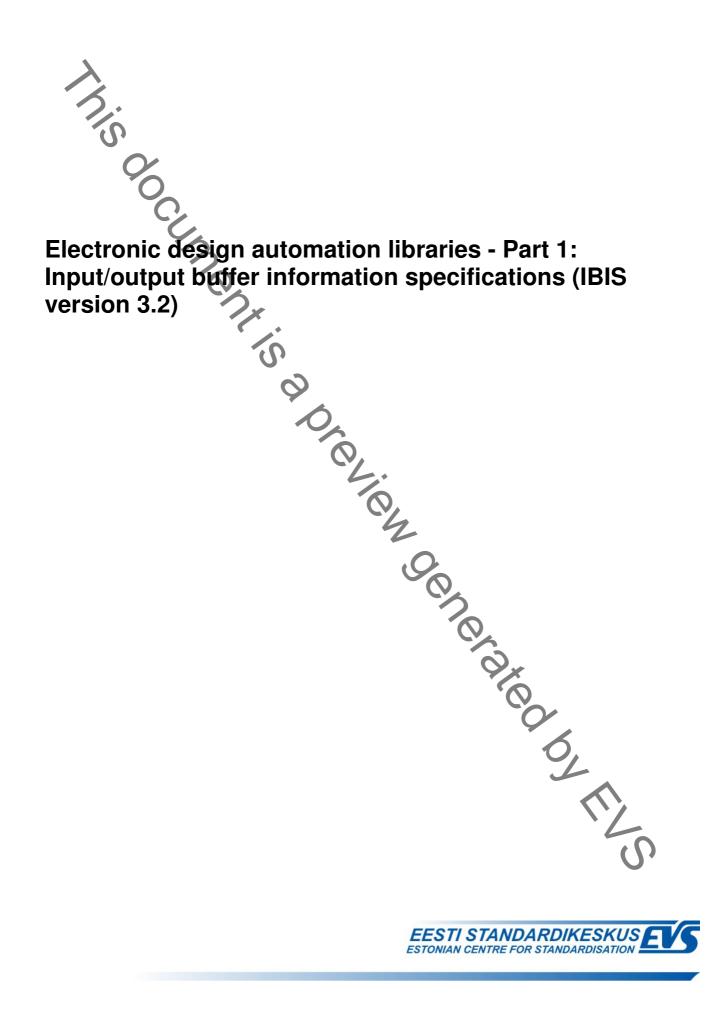
# **EESTI STANDARD**



## EESTI STANDARDI EESSÕNA

## NATIONAL FOREWORD

Käesolev Eesti standard EVS-EN 62014-1:2003 sisaldab Euroopa standardi EN 62014-1:2002	This Estonian standard EVS-EN 62014-1:2003 consists of the English text of the European
ingliskeelset teksti.	standard EN 62014-1:2002.
Standard on kinnitatud Eesti Standardikeskuse 05.02.2003 käskkirjaga ja jõustub sellekohase teate avaldamiset EVS Teatajas.	This standard is ratified with the order of Estonian Centre for Standardisation dated 05.02.2003 and is endorsed with the notification published in the official bulletin of the Estonian national standardisation organisation.
Euroopa standardimisorganisatsioonide poolt rahvuslikele liikmetele Euroopa standardi teksti kättesaadavaks tegemise kuupäev on 11.01.2002.	Date of Availability of the European standard text 11.01.2002.
Standard on kättesaadav Eesti standardiorganisatsioonist.	The standard is available from Estonian standardisation organisation.
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## EUROPEAN STANDARD

# EN 62014-1

## NORME EUROPÉENNE

## EUROPÄISCHE NORM

January 2002

ICS 25 English version **Electronic design automation libraries** Part 1: Input/Output buffer information specifications (IBIS version 3.2) (IEC 62014-1:2001) Automatisation de la conception -Bibliotheken für die **Bibliothèques** Entwurfsautomatisierung Partie 1: Spécifications des informations Teil 1: Spezifikation von Eigenschaften von I/O Buffern en entrée/sortie des circuits tampon (IBIS Version 3.2) (IBIS version 3.2) (CEI 62014-1:2001) (IEC 62014-1:2001) This European Standard was approved by CENELEO on 2001-07-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration. Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member This European Standard exists in two official versions (English, French). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions. CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxenbourg, Malta, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom. 52 CENELEC European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung Central Secretariat: rue de Stassart 35, B - 1050 Brussels

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### Foreword

The text of document 93/129/FDIS, future edition 1 of IEC 62014-1, prepared by IEC TC 93, Design automation, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62014-1 on 2001-07-01.

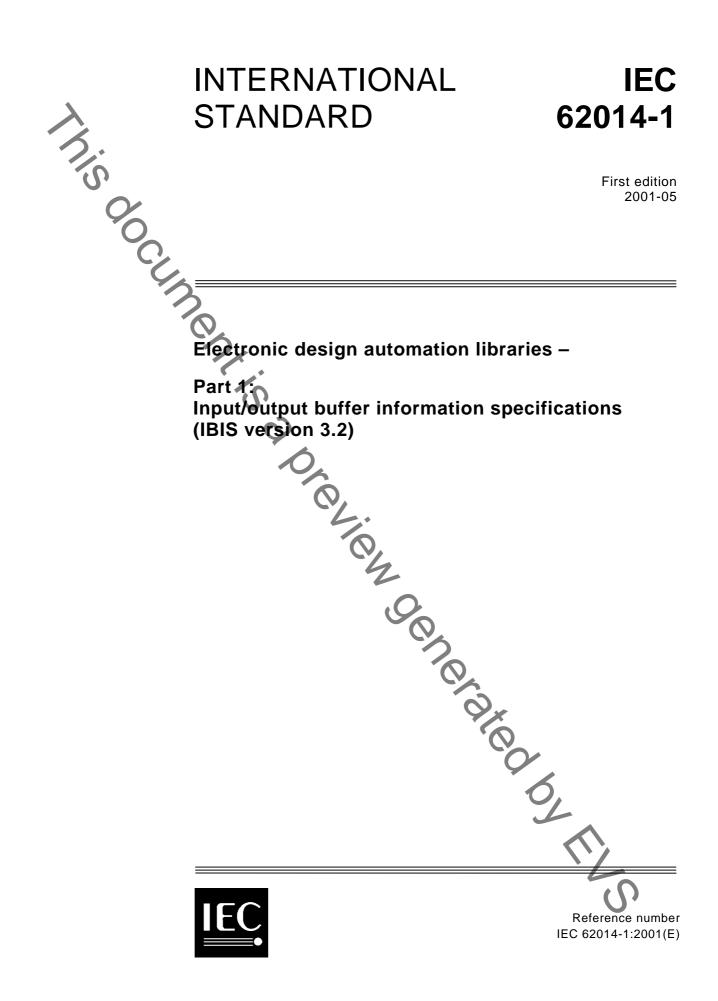
The following dates were fixed:

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– late	est date by which the EN has to be implemented			
at r	national level by publication of an identical			
nat	ional standard or by endorsement	(dop)	2002-07-01	
– late	est date by which the national standards conflicting			
	h the EN have to be withdrawn	(dow)	2004-07-01	
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## **Endorsement notice**

The text of the International Standard IEC 62014-1:2001 was approved by CENELEC as a European Standard without any modification.

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## **Publication numbering**

As from 1 January 1997 all IEC publications are issued with a designation in the 60000 series. For example, IEC 34-1 is now referred to as IEC 60034-1.

## Consolidated editions

The IEC is now publishing consolidated versions of its publications. For example, edition numbers 1.0, 1.1 and 1.2 refer, respectively, to the base publication, the base publication incorporating amendment 1 and the base publication incorporating amendments 1 and 2.

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The technical content of IEC publications is kept under constant review by the IEC, thus ensuring that the content reflects current technology. Information relating to this publication, including its validity, is available in the IEC Catalogue of publications (see below) in addition to new editions, amendments and corrigenda. Information on the subjects under consideration and work in progress undertaken by the technical committee which has prepared this publication, as well as the list of publications issued, is also available from the following:

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The on-line catalogue on the IEC web site (<u>www.iec.ch/catlg-e.htm</u>) enables you to search by a variety of criteria including text searches, technical committees and date of publication. On-line information is also available on recently issued publications, withdrawn and replaced publications, as well as corrigenda.

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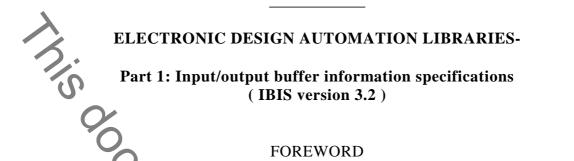
Email: custserv@iec.ch Tel: +41 22 919 02 11 Fax: +41 22 919 03 00



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Section 9: Notes on data derivation method	

## INTERNATIONAL ELECTROTECHNICAL COMMISSION



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International Standard IEC 62014-1 has been prepared by IEC technical committee 93: Design Automation

This standard is based on ANSI-EIA-656-A (September 1999): 1/0 buffer information specifications (IBIS) version 3.2

The text of this standard is based on the following documents:

FDIS	Report on voting	X
93/129/FDIS	93/136/RVD	

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This standard does not follow the rules for the structure of international standards given in Part 3 of the ISO/IEC Directives.

IEC 62014 consists of the following parts:

IEC 62014-1, Electronic design automation libraries – Part 1: Input/Output buffer information specifications (IBIS version 3.2)

IEC 62014-2, *Electronic design automation libraries – Part 2: Library standard architectures* (TR)(under consideration)

IEC 62014-3, Electronic design automation libraries – Part 3: Modules of integrated circuits for EMI Behavioural simulation (under consideration)

The committee has decided that the contents of this publication will remain unchanged until 2004. At this date, the publication will be

- reconfirmed;
- withdrawn;
- A Cocument is a preview denerated by the first of the fir replaced by a revised edition, or
- amended.

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### **INTRODUCTION**

### **Background of IBIS**

IBIS was first developed at Intel Corporation and has been expanded to its current form (Version 3.2) through the cooperative efforts of additional analog simulator vendors, computer manufacturers, IC vendors, commercial users, and universities. In May 1993, the group formed itself into the IBIS Open Forum, an open, voluntary, cooperative association. In March 1995, the group affiliated with the EIA (now the Electronic Industries Alliance) as the EIA IBIS Open Forum.

The Forum has been and continues to meet via teleconference approximately every third week to propose updates to the IBIS standard, to help new participants, and to advance the standard. The Forum also meets in person about four times a year to exchange ideas and conduct official business.

Most of the Forum activities are handled through e-mail discussions using a reflector "ibis@eda.org." A users group reflector "ibis-users@eda.org" is also supported for users of IBIS. One can get more information on subscribing to the reflectors and to other ongoing Forum activities through the official web page: "http://www.eigroup.org/ibis/ibis.htm". The process of making changes and improvements to IBIS is through a "BIRD" (Buffer Issue Resolution

Document) process involving approval by the Forum voting members. Over the years the Forum has grown to over thirty voting members (requiring a modest yearly fee for administrative support), but the Forum also maintains an open, public communications policy and welcomes all interested participants regardless of membership status.

Through official EIA and ANSI (American National Standards Institution) public letter ballot processes, IBIS Version 2.1 was ratified as ANSI/EIA-656 in December 13, 1995. Version 1.1 of IBIS focused on TTL and CMOS logic components. Although never officially ratified as a national standard, IBIS Version 1.1 served as a basis for advances in Version 2.1 to increase its accuracy and number of device types that are supported.

Version 2.1 contains the following advances:

- Controlled slew rate devices
- ECL and PECL technologies
- Independent control over power rails so RS232 and other types of devices with multiple rails can be modeled
- Differential drivers and devices
- Open-drain I/O devices such as open drain and open collector devices
- Expanded package model definitions to include coupling between pins.

The Forum also voluntarily funded a parser development activity through the sale of source code licenses of "ibischk2" and has made executables of the parser code freely and publicly available to enable IBIS model checking.

Industrial advances associated with new semiconductor topologies, package design and measurement needs kept the Forum busy proposing new capabilities, eventually leading to IBIS Version 3.2. Again through official EIA and ANSI public letter ballot processes, IBIS Version 3.2 was ratified as ANSI/EIA-656-A on September 21, 1999.

Its advances include the following:

- Series and series switch models
- Multi-stage driver capability for phased stages

- Submodel capability supporting dynamic clamps and bus hold functions for active and dynamic terminations
- More specification values for overshoot and pulse immunity
- Uncoupled packages with sections and forks
- Uncoupled advanced packages known as electrical board descriptions with sections, forks and onboard components.

IBIS Version 3.2 has complied with an original Forum objective that all subsequent versions of IBIS be backward compatible with previous versions.

The Forum funded through voluntary source code license purchases the corresponding "ibischk3" parser and has made its executables freely available.

The IBIS Standard has achieved wide spread national and international support and recognition as indicated by over 40 semiconductor vendors providing IBIS models freely from their web sites. Many more IBIS models and libraries are available from commercial vendors and directly through IC vendor sales organizations. While IBIS models can be of value in all phases of a design and analysis process, they are particularly suitable for printed circuit board design tools used in conjunction with the corresponding physical and mechanical data bases describing the boards.

### **Future IBIS Directions**

Technology continues to advance, forcing more stringent electrical requirements and newer ways of doing things. The Forum is keeping up with such advances. However, its strategy has shifted. Up to now the Forum has been adding to the existing fixed-format IBIS document. Such a process is slow and subject to unexpected interactions with existing capability. The newer approach is to create a compatible macro-language that allows more rapid reconfiguration and response to changing needs.

While the Forum has not yet ratified any of these approaches, it is pursuing these projects:

- A macro-language that fully supports IBIS Version 3.2 but can also support more advanced features and nodal component structures
- A separate Connector Specification with advanced coupled stages to support key component used to connect printed circuit boards (and possibly be used for more advanced package models)
- Some further advances in specification details beyond IBIS Version 3.2.

These projects advance the capability of IBIS in a manner that supports the existing IBIS Version 3.2 functionality, but also allows for much more rapid implementation of new requirements.

### References

ANSI/EIA-656: IBIS Version 2.1 released December 13, 1995

ANSI/EIA-656-A: IBIS Version 3.2 released September 21, 1999



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## Section 1

GENERAL INTRODUCTION

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This section gives a general overview of the remainder of this document.

Sections 2 and 3 contain general information about the IBIS versions and the general rules and guidelines. Several progressions of IBIS documents are referenced in Section 2 and in the discussion below. They are IBIS Version 1.1 (ratified August, 1993), IBIS Version 2.1 (ratified as ANSI/EIA-656 in December, 1995), and IBIS Version 3.2 (this document ratified in August (1999).

The functionality of IBIS follows in Sections 4 through 8. Sections 4 through 6 describe the format of the core functionality of IBIS Version 1.1 and the extensions in later versions. The data in these sections are contained in .ibs files. Section 7 describes the package model format of IBIS Version 2.1 and a subsequent extension. Package models can be formatted within .ibs files or can be formatted (along with the Section 4 file header keywords) as .pkg files. Section 8 contains the Electrical Board Description format of IBIS Version 3.2. Along with Section 4 header information, electrical board descriptions must be described in separate .ebd files.

Section 9 contains some notes regarding the extraction conditions and data requirements for IBIS files. This section focuses on implementation conditions based on measurement or simulation for gathering the IBIS compliant data. 

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Section 2
STATEMENT OF INTENT
In order to enable an industry standard method to electronically transport IBIS Modeling Data between semiconductor vendors, simulation vendors, and end customers, this template is proposed. The intention of this template is to specify a consistent format that can be parsed by software, allowing simulation vendors to derive models compatible with their own products. One goal of this template is to represent the current state of IBIS data, while allowing a growth path to more complex models / methods (when deemed
appropriate). This would be accomplished by a revision of the base template, and possibly the addition of new keywords or categories.
Another goal of this template is to ensure that it is simple enough for semiconductor vendors and customers to use and modify, while ensuring that it is rigid enough for simulation vendors to write reliable parsers.
Finally, this template is meant to contain a complete description of the I/O elements on an entire component. Consequently, several models will need to be defined in each file, as well as a table that equates the appropriate buffer to the correct pin and signal name.
Version 3.2 of this electronic template was finalized by an industry-wide group of experts representing various companies and interests. Regular "EIA IBIS Open Forum" meetings were held to accomplish this task.
Commitment to Backward Compatibility. Version 1.0 is the first valid IBIS ASCII file format. It represents the minimum amount of I/O buffer information required to create an accurate IBIS model of common CMOS and bipolar I/O structures. Future revisions of the ASCII file will add items considered to be "enhancements" to Version 1.0 to allow accurate modeling of new, or other I/O buffer structures. Consequently all future revisions will be considered supersets of Version 1.0, allowing backward compatibility. In addition, as modeling platforms develop support for revisions of the IBIS ASCII template, all previous revisions of the template must also be supported.
Version 1.1 update. The file "ver1_1.ibs" is conceptually the same as the 1.0 version of the IBIS ASCII format (ver1_0.ibs). However, various comments have been added for further clarification.
Version 2.0 update. The file "ver2_0.ibs" maintains backward compatibility with Versions 1.0 and 1.1. All new keywords and elements added in Version 2.0 are optional. A complete list of changes to the specification is in the IBIS Version 2.0 Release Notes document ("ver2_0.rn").
Version 2.1 update. The file "ver2_1.ibs" contains clarification text Cr changes, corrections, and two additional waveform parameters beyond Version 2.0.

Version 3.0 update. The file "ver3\_0.ibs" adds a number of new keywords and functionality. A complete list of functions can be found on eda.org under /pub/ibis/birds/birddir.txt showing the approved Buffer Issue Resolution Documents (BIRDs) that have been approved for Version 3.0.

Version 3.1 update. The file "ver3\_1.ibs" contains a major reformatting of the document and a simplification of the wording. It also contains some new technical enhancements that were unresolved when Version 3.0 was approved.

Version 3.2 update. The file "ver3\_2.ibs" adds more technical advances and also a number of editorial changes documented in 12 BIRDs and also in also a number of editorial charges documented in 12 BIRUS and also in responses to hubic letter ballot comments. responses to public letter ballot comments.

e file "ver3 0.ibs" adds a r

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>	Section 3
G	ENERAL SYNTAX RULES AND GUIDELINES
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Thi: fil	s section contains general syntax rules and guidelines for ASCII IBIS es:
1)	The content of the files is case sensitive, except for reserved words and keywords.
2)	The following words are reserved words and must not be used for any other purposes in the document: POWER - reserved model name, used with power supply pins,
	<pre>GND - reserved model name, used with ground pins, NC - reserved model name, used with no-connect pins, NA - used where data not available.</pre>
3)	To facilitate portability between operating systems, file names used in the IBIS file must only have lower case characters. File names should have a basename of no more than twenty characters followed by a period ('.'), followed by a file name extension of no more than three characters. The file name and extension must use characters from the set (space, ' ', 0x20 is not included):
	abcdefghijklmnopqrstuvwxyz 0 1 2 3 4 5 6 7 8 9 _ ^ \$ ~ ! # % & - { } ) (@ ' `
	The file name and extension are recommended to be lower case on systems that support such names.
4)	A line of the file may have at most 80 characters, followed by a line termination sequence. The line termination sequence must be one of the following two sequences: a linefeed character, or a carriage return followed by linefeed character.
5)	Anything following the comment character is ignored and considered a comment on that line. The default " " (pipe) character can be changed by the keyword [Comment Char] to any other character. The [Comment Char] keyword can be used throughout the file as desired.
6)	Keywords must be enclosed in square brackets, [], and must start in column 1 of the line. No space or tab is allowed immediately after the opening bracket '[' or immediately before the closing bracket ']'. If used, only one space (' ') or underscore ('_') character separates the parts of a multi-word keyword.
7)	Underscores and spaces are equivalent in keywords. Spaces are not allowed in subparameter names.